

STGW45HF60WDI

45 A, 600 V ultra fast IGBT

Preliminary data

Features

- Improved E_{off} at elevated temperature
- Low C_{RES} / C_{IES} ratio (no cross-conduction susceptibility)
- Low V_F soft recovery antiparallel diode

Applications

- Welding
- Induction heating
- Resonant converters

Description

The "HF" series is based on a new planar technology concept to yield an IGBT with tighter variation of switching energy (E_{off}) versus temperature. Suffix "W" denotes a subset of products tailored to high switching frequency operation over 100 kHz.

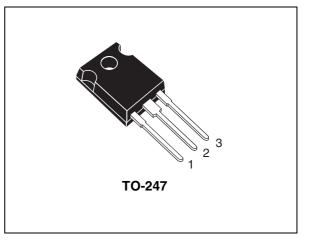


Figure 1. Internal schematic diagram

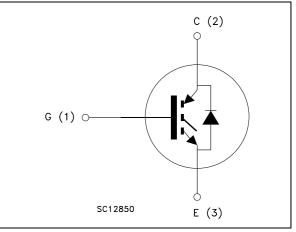


Table 1. Device summary

Order code	Marking	Package	Packaging
STGW45HF60WDI	GW45HF60WDI	TO-247	Tube
STGWA45HF60WDI	45HF60WDI	TO-247 long leads	lube

This is preliminary information on a new product now in development or undergoing evaluation. Details are subject to change without notice.

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Electrical ratings

Table 2. A	bsolute	maximum	ratings
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Symbol	Parameter		Unit		
Symbol	Falameter	TO-247	TO-247 long leads		
V _{CES}	Collector-emitter voltage ($V_{GE} = 0$)	600		V	
I _C ⁽¹⁾	Continuous collector current at $T_C = 25 \ ^{\circ}C$	70	80	Α	
I _C ⁽¹⁾	Continuous collector current at T _C = 100 °C	45	50	Α	
I _{CL} ⁽²⁾	Turn-off latching current	TBD		Α	
I _{CP} ⁽³⁾	Pulsed collector current	TBD		Α	
V _{GE}	Gate-emitter voltage		± 20	V	
١ _F	Diode RMS forward current at T_{C} = 25 °C		30	Α	
I _{FSM}	Surge not repetitive forward current t _p = 10 ms sinusoidal	130		A	
P _{TOT}	Total dissipation at $T_C = 25 \ ^{\circ}C$	250 310		W	
T _{stg}	Storage temperature	- 55 to 150		°C	
Тj	Operating junction temperature	_	55 10 150	C	

1. Calculated according to the iterative formula:

$$I_{C}(T_{C}) = \frac{T_{j(max)} - T_{C}}{R_{thj-c} \times V_{CE(sat)(max)}(T_{j(max)}, I_{C}(T_{C}))}$$

2. Pulse width limited by maximum junction temperature and turn-off within RBSOA

3. V_{CLAMP} = 80% (V_{CES}), V_{GE} = 15 V, R_{G} = 10 $\Omega,\,T_{J}$ = 150 $^{\circ}C$

Table 3. Thermal data

Symbol	Parameter		Unit	
Symbol	Falameter	TO-247	TO-247 long leads	Unit
Б	Thermal resistance junction-case IGBT	0.5	0.4	°C/W
R _{thj-case}	Thermal resistance junction-case diode 1.5		1.5	°C/W
R _{thj-amb}	Thermal resistance junction-ambient	50		°C/W



2 Electrical characteristics

(T_J = 25 °C unless otherwise specified)

Table 4.	Static					
Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V _{(BR)CES}	Collector-emitter breakdown voltage (V _{GE} = 0)	I _C = 1 mA	600			V
V _{CE(sat)}	Collector-emitter saturation voltage	$V_{GE} = 15 \text{ V}, \text{ I}_{C} = 30 \text{ A}$ $V_{GE} = 15 \text{ V}, \text{ I}_{C} = 30 \text{ A}, \text{T}_{J} = 125 \text{ °C}$		1.9 TBD	2.5	V V
V _{GE(th)}	Gate threshold voltage	$V_{CE} = V_{GE}, I_C = 1 \text{ mA}$	3.75		5.75	V
I _{CES}	Collector cut-off current $(V_{GE} = 0)$	V _{CE} = 600 V V _{CE} = 600 V, T _J = 125 °C			500 5	μA mA
I _{GES}	Gate-emitter leakage current (V _{CE} = 0)	V _{GE} = ±20 V			± 100	nA
9 _{fs}	Forward transconductance	$V_{CE} = 15 \text{ V}, \text{ I}_{C} = 30 \text{ A}$		TBD		S

Table 4. Static

Table 5. Dynamic

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
C _{ies} C _{oes} C _{res}	Input capacitance Output capacitance Reverse transfer capacitance	V _{CE} = 25 V, f = 1 MHz, V _{GE} = 0	-	TBD TBD TBD	-	pF pF pF
Q _g Q _{ge} Q _{gc}	Total gate charge Gate-emitter charge Gate-collector charge	V_{CE} = 390 V, I _C = 30 A, V _{GE} = 15 V, <i>Figure 3</i>	-	TBD TBD TBD	-	nC nC nC



Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
t _{d(on)} t _r (di/dt) _{on}	Turn-on delay time Current rise time Turn-on current slope	$V_{CC} = 390 \text{ V}, \text{ I}_{C} = 30 \text{ A}$ $\text{R}_{\text{G}} = 4.7 \Omega, \text{ V}_{\text{GE}} = 15 \text{ V},$ $\textit{Figure 2}$	-	TBD TBD TBD	-	ns ns A/µs
t _{d(on)} t _r (di/dt) _{on}	Turn-on delay time Current rise time Turn-on current slope	$V_{CC} = 390 \text{ V}, I_{C} = 30 \text{ A}$ $R_{G} = 4.7 \Omega, V_{GE} = 15 \text{ V},$ $T_{J} = 125 \text{ °C}$ Figure 2	-	TBD TBD TBD	-	ns ns A/µs
$t_r(V_{off}) \ t_d(_{off}) \ t_f$	Off voltage rise time Turn-off delay time Current fall time	$V_{CC} = 390 \text{ V}, I_C = 30 \text{ A},$ $R_{GE} = 4.7 \Omega, V_{GE} = 15 \text{ V}$ <i>Figure 2</i>	-	TBD TBD TBD	-	ns ns ns
t _r (V _{off}) t _d (_{off}) t _f	Off voltage rise time Turn-off delay time Current fall time	$V_{CC} = 390 \text{ V}, I_C = 30 \text{ A},$ $R_{GE} = 4.7 \Omega, V_{GE} = 15 \text{ V},$ $T_J = 125 \text{ °C}$ <i>Figure 2</i>	-	TBD TBD TBD	-	ns ns ns

 Table 6.
 Switching on/off (inductive load)

 Table 7.
 Switching energy (inductive load)

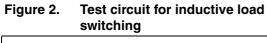
Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
E _{off}	Turn-off switching losses	V_{CC} = 390 V, I _C = 30 A R _G = 4.7 Ω , V _{GE} = 15 V, <i>Figure 4</i>	-	330		μJ
E _{off}	Turn-off switching losses	$V_{CC} = 390 \text{ V}, I_{C} = 30 \text{ A}$ $R_{G} = 4.7 \Omega, V_{GE} = 15 \text{ V},$ $T_{J} = 125 \text{ °C}, Figure 4$	-	550	800	μJ

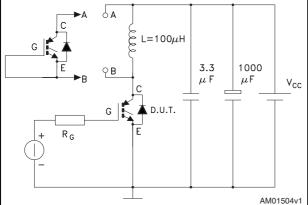
Table 8. Collector-emitter diode

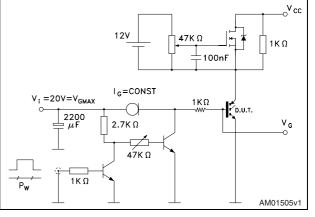
Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V _F	Forward on-voltage	I _F = 30 A I _F = 30 A, T _J = 125 °C	-	1.4 1.2	1.8	V V
t _{rr} Q _{rr} I _{rrm}	Reverse recovery time Reverse recovery charge Reverse recovery current	I _F = 30 A,V _R = 50 V, di/dt = 100 A/μs <i>Figure 5</i>	-	TBD TBD TBD	-	ns nC A
t _{rr} Q _{rr} I _{rrm}	Reverse recovery time Reverse recovery charge Reverse recovery current	$I_F = 30 \text{ A}, V_R = 50 \text{ V},$ $T_J = 125 \text{ °C}, \text{ di/dt} = 100 \text{ A/}\mu\text{s}$ <i>Figure 5</i>	-	TBD TBD TBD	-	ns nC A



3 Test circuits







Gate charge test circuit





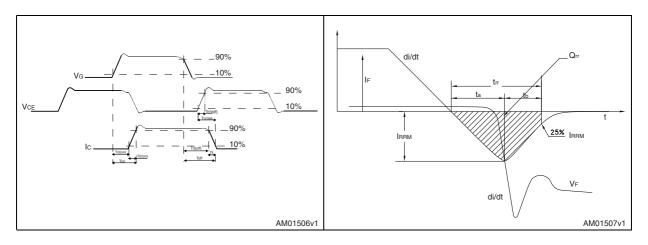


Figure 3.

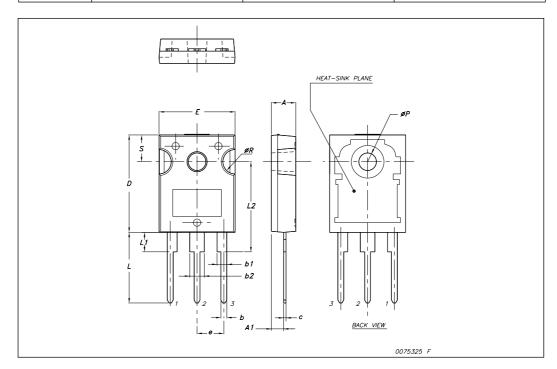


4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.



	TO-247 Mechanical data				
Dim.		mm.			
Dini	Min.	Тур	Max.		
А	4.85		5.15		
A1	2.20		2.60		
b	1.0		1.40		
b1	2.0		2.40		
b2	3.0		3.40		
С	0.40		0.80		
D	19.85		20.15		
E	15.45		15.75		
е		5.45			
L	14.20		14.80		
L1	3.70		4.30		
L2		18.50			
øP	3.55		3.65		
øR	4.50		5.50		
S		5.50			

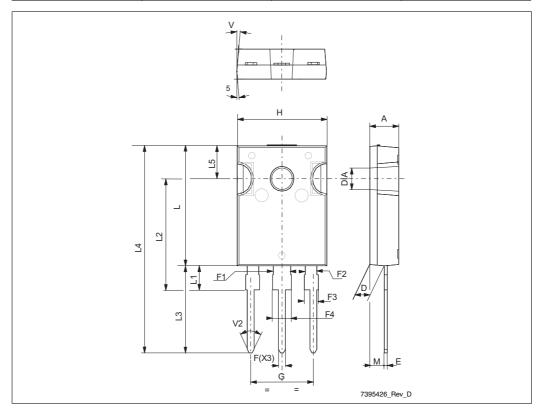




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TO-247 long leads mechanical data				
Dim.	mm			
Dim.	Min.	Тур.	Max.	
А	4.85		5.16	
D	2.2		2.6	
E	0.4		0.8	
F	1		1.4	
F1		3		
F2		2		
F3	1.9		2.4	
F4	3		3.4	
G		10.9		
Н	15.45		16.03	
L	19.85		21.09	
L1	3.7		4.3	
L2	18.3		19.13	
L3	14.2		20.3	
L4	34.05		41.38	
L5	5.35		6.3	
М	2		3	
V		5°		
V2		60°		
DIAM	3.55		3.65	



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5 Revision history

Table 9.Document revision history

Date	Revision	Changes
04-Aug-2009	1	Initial release.



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